

DATA SHEET

CURRENT SENSOR-LOW TCR

PT-High power series

5%,1%

size 2010

RoHS Compliant



Phicomp

Product specification



SCOPE

This specification describes PT2010 current sensor – low TCR chip resistors with lead-free terminations made by thick film process.

APPLICATIONS

- Power supplies
- Consumer(Mobile 、 PNDs 、 ...)
- Laptop
- HDDs

FEATURES

- Products with lead free terminations meet RoHS requirements.
- High component and equipment reliability with high power rating (1W).
- Low resistance (100mΩ or under)and narrow tolerance (±1%) can suitable for current detection.

ORDERING INFORMATION - GLOBAL PART NUMBER

Part number is identified by the series name, size, tolerance, packaging type, temperature coefficient of resistance, taping reel, resistance value.

PT2010	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>XXXX</u>	<u>L</u>
	(1)	(2)	(3)	(4)	(5)	(6)	(7)

(1) TOLERANCE

F = ±1%

J = ±5%

(2) PACKAGING TYPE

K = Embossed taping reel

(3) TEMPERATURE COEFFICIENT OF RESISTANCE

— = base on spec

(4) TAPING REEL

7 = 7 inch dia. Reel

(5) POWER RATING

W = 2 x standard power

(6) RESISTANCE VALUE

PT2010: 0R1 to 0R91

(7) OPTIONAL CODE

L = optional symbol_(NOTE)

ORDERING EXAMPLE

The ordering code for a PT2010 1W chip resistor, value 0.22Ω with ±1% tolerance, supplied in 7-inch tape reel with 4Kpcs quantify is:

PT2010FR-7W0R22L.

NOTE

1. All our RSMD products meet RoHS compliant and Halogen Free. "LFP" of the internal 2D reel label mentions "Lead Free Process"



MARKING

PT2010: E-24 SERIES



3 digits

The “R” is used as a decimal point; the other 2 digits are significant.

CONSTRUCTION

The resistors are constructed out of a high-grade ceramic body. Internal metal electrodes are added at each end and connected by a resistive paste. The composition of the paste is adjusted to give the approximate required resistance and laser cutting of this resistive layer that achieves tolerance trims the value. The resistive layer is covered with a protective coat and printed with the resistance value. Finally, the two external terminations (matte tin) are added. See fig. 2.

DIMENSIONS

Table 1	
TYPE	PT2010
L (mm)	5.00±0.10
W (mm)	2.50±0.15
H (mm)	0.55±0.10
l1 (mm)	0.60±0.20
l2 (mm)	0.50±0.20

OUTLINES

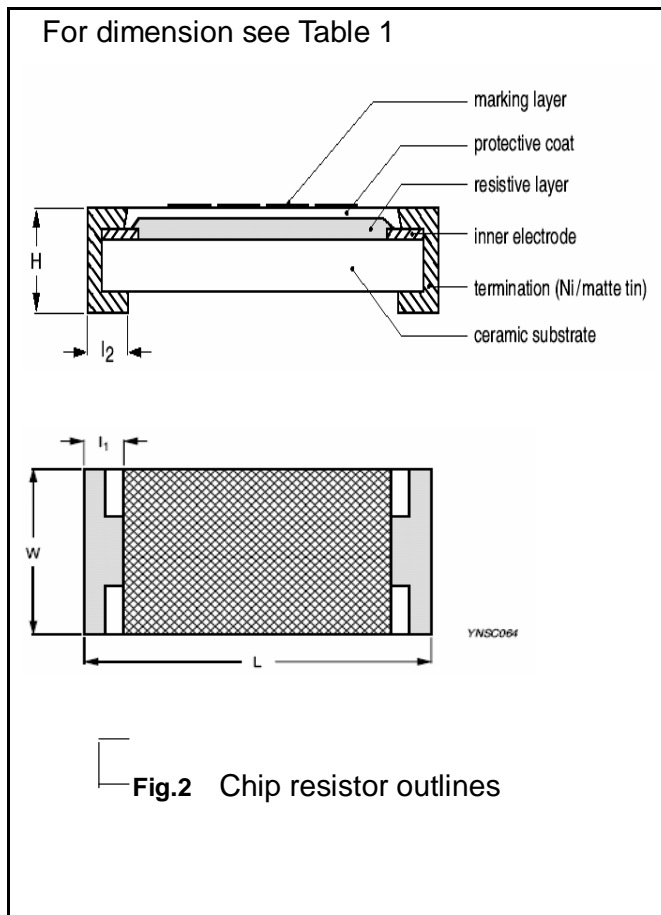


Fig.2 Chip resistor outlines

ELECTRICAL CHARACTERISTICS

Table 2

CHARACTERISTICS	PT2010	1W
Operating Temperature Range	-55°C to +125°C	
Maximum Working Voltage	$\sqrt{(P * R)}$	
Resistance Range	PT2010 : 100mΩ to 910mΩ	
Temperature Coefficient	100mΩ	>100mΩ
	±100ppm/°C	±75ppm/°C

PACKING STYLE AND PACKAGING QUANTITY

Table 3

PRODUCT TYPE	PACKING STYLE	REEL DIMENSION	QUANTITY PER REEL
PT2010	K = Embossed taping reel	7" (178 mm)	4,000 Units

FUNCTIONAL DESCRIPTION

POWER RATING

PT2010 rated power at 70°C is 1W

RATED VOLTAGE

The DC or AC (rms) continuous working voltage corresponding to the rated power is determined by the following formula:

$$V = \sqrt{(P * R)}$$

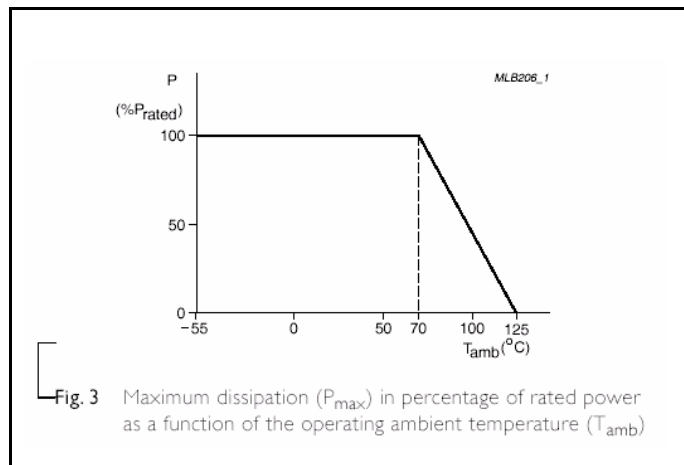
Where

V=Continuous rated DC

or AC (rms) working voltage (v)

P=Rated power

R=Resistance value (Ω)



TAPING REEL

Table 4

DIMENSION	2010
Tape Width(mm)	12
ØA (mm)	180+0/-3
ØN (mm)	60+1/-0
ØC (mm)	13.5±0.5
ØD (mm)	21.0±0.8
W1 (mm)	13.6±0.5
W2 (mm)	16.5±0.5

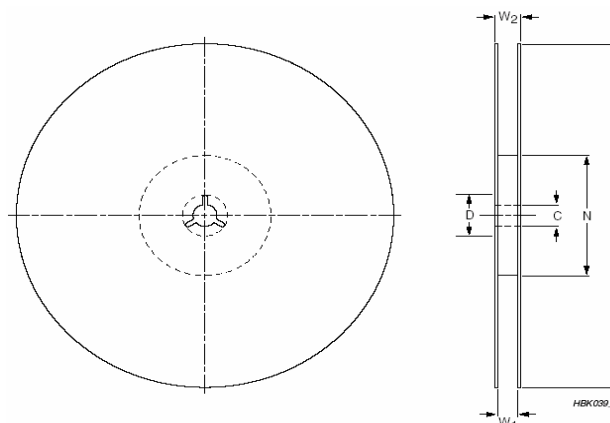


Fig.4 Reel

PAPER/PE TAPE SPECIFICATION

Table 5

DIMENSION	2010
A ₀ (mm)	2.8±0.2
B ₀ (mm)	5.4±0.2
W (mm)	12±0.2
E (mm)	1.75±0.1
F (mm)	5.5±0.05
P ₀ (mm)	4.0±0.1
P ₁ (mm)	4.0±0.1
P ₂ (mm)	2.0±0.05
D ₀ (mm)	1.5+0.1/-0
T (mm)	1.5+0.25/-0

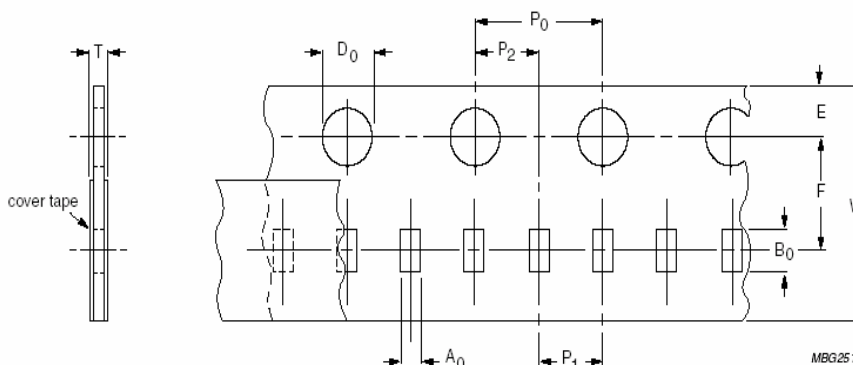


Fig.5 Paper/PE tape

PACKING METHOD

LEADER/TRAILER TAPE SPECIFICATION

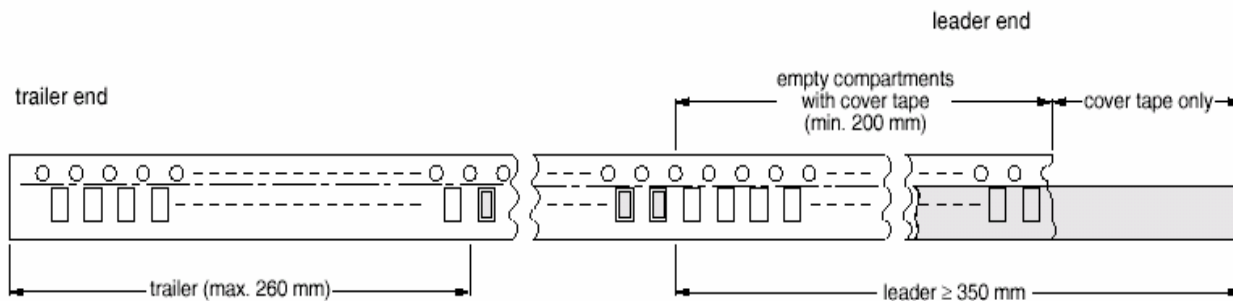


Fig.6 Leader/trailer tape



TESTS AND REQUIREMENTS

TEST	TEST METHOD	PROCEDURE	REQUIREMENT
Life/ Endurance	IEC 60115-1 4.25.1	1,000 hours at 70±5 °C applied RCWV 1.5 hours on, 0.5 hour off, still air required	± (1.0 % + 0.0005 Ω)
High Temperature Exposure/ Endurance at upper category temperature	IEC 60068-2-2	1,000 hours at 155±5 °C,unpowered	± (1.0 % + 0.0005 Ω)
Moisture Resistance	MIL-STD-202 Method 106G	Each temperature / humidity cycle is defined at 8 hours (Method 106G), 3 cycles / 24 hours for 10d. with 25 °C / 65 °C 95% R.H, without steps 7a & 7b, un-powered Parts mounted on test-boards, without condensation on parts Measurement at 24±2 hours after test conclusion.	± (0.5% + 0.0005 Ω)
Thermal Shock	MIL-STD-202G Method 107G	-55/+125 °C Note: Number of cycles required is 300. Devices unmounted Maximum transfer time is 20 seconds. Dwell time is 15 minutes. Air – Air	± (1.0% + 0.0005 Ω)
Short time overload	IEC 60115-1 4.13	2.5 times of rated voltage or maximum overload voltage whichever is less for 5 sec at room temperature	± (1.0% + 0.0005 Ω) No visible damage
Board Flex/ Bending	IEC 60068-2-21	Chips mounted on a 90mm glass epoxy resin PCB(FR4) 2 mm bending Bending time: 60±1 seconds	± (1.0 % + 0.0005 Ω)
Solderability - Wetting	IPC/JEDEC J-STD-002B test B	Electrical Test not required Magnification 50X SMD conditions: 1st step: Method B, aging 4 hours at 155 °C dry heat 2nd step: leadfree solder bath at 245±3 °C Dipping time: 3±0.5 seconds	Well tinned (≥95% covered) No visible damage
- Leaching	IPC/JEDEC J-STD-002B test D	Leadfree solder, 260 °C, 30 seconds immersion time	No visible damage
- Resistance to Soldering Heat	IEC 60068-2-58	Condition B, no pre-heat of samples Leadfree solder, 260±5 °C, 10±1seconds immersion time Procedure 2 for SMD: devices fluxed and cleaned with isopropanol	± (0.5% + 0.0005 Ω) No visible damage



REVISION HISTORY

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version 0	2009-03-13		- First issue of this specification